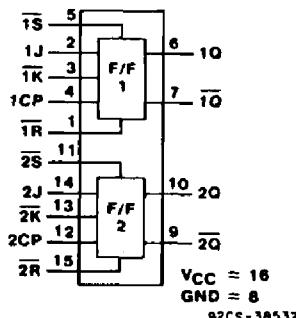




Data sheet acquired from Harris Semiconductor
SCHS282

CD54/74AC109, CD54/74AC112 CD54/74ACT109, CD54/74ACT112



**CD54/74AC/ACT109
FUNCTIONAL DIAGRAM**

Dual "J-K" Flip-Flop with Set and Reset

CD54/74AC/ACT109 - Positive-Edge-Triggered (J, K)

CD54/74AC/ACT112 - Negative-Edge-Triggered (J, K)

Type Features:

- Buffered inputs
- Typical propagation delay:
4.8 ns @ $V_{cc} = 5$ V, $T_A = 25^\circ\text{C}$, $C_L = 50 \mu\text{F}$

The RCA CD54/74AC109 and CD54/74AC112 and the CD54/74ACT109 and CD54/74ACT112 dual "J-K" flip-flops with set and reset use the RCA ADVANCED CMOS technology. These flip-flops have independent J, K (or \bar{K}), Set, Reset, and Clock inputs and Q and \bar{Q} outputs. The CD54/74AC/ACT112 changes state on the negative-going transition of the clock pulse. The CD54/74AC/ACT109 changes state on the positive-going transition of the clock. Set and Reset are accomplished asynchronously by low-level inputs.

The CD74AC/ACT109 and CD74AC/ACT112 are supplied in 16-lead dual-in-line plastic packages (E suffix) and in 16-lead dual-in-line small-outline plastic packages (M suffix). Both package types are operable over the following temperature ranges: Commercial (0 to 70°C); Industrial (-40 to $+85^\circ\text{C}$); and Extended Industrial/Military (-55 to $+125^\circ\text{C}$).

The CD54AC/ACT109 and CD54AC/ACT112, available in chip form (H suffix), are operable over the -55 to $+125^\circ\text{C}$ temperature range.

Family Features:

- Exceeds 2-kV ESD Protection - MIL-STD-883, Method 3015
- SCR-Latchup-resistant CMOS process and circuit design
- Speed of bipolar FAST®/AS/S with significantly reduced power consumption
- Balanced propagation delays
- AC types feature 1.5-V to 5.5-V operation and balanced noise immunity at 30% of the supply
- $\pm 24\text{-mA}$ output drive current
 - Fanout to 15 FAST® ICs
 - Drives 50-ohm transmission lines

*FAST is a Registered Trademark of Fairchild Semiconductor Corp.

CD54/74AC/ACT109 TRUTH TABLE

INPUTS					OUTPUTS	
\bar{S}	\bar{R}	CP	J	K	Q	\bar{Q}
L	H	X	X	X	H	L
H	L	X	X	X	L	H
L	L	X	X	X	H'	H'
H	H	—	L	L	L	H
H	H	—	H	L	TOGGLE	
H	H	—	L	H	NO CHANGE	
H	H	—	H	H	H	L
H	H	L	X	X	NO CHANGE	

*Unpredictable and unstable condition if both \bar{S} and \bar{R} go high simultaneously.

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This data sheet is applicable to the CD54/74AC109, CD54AC112, CD45ACT109, and CD54ACT112. See SCHS233 for information on the CD74AC112, CD74ACT109, and CD74ACT112.

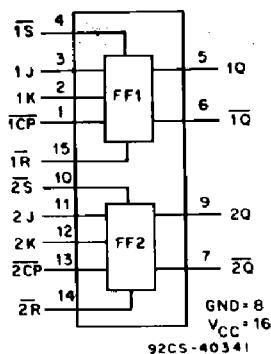
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CD54/74AC109, CD54/74AC112

CD54/74ACT109, CD54/74ACT112

CD54/74AC/ACT112 TRUTH TABLE

INPUTS					OUTPUTS	
S	R	CP	J	K	Q	Q̄
L	H	X	X	X	H	L
H	L	X	X	X	L	H
L	L	X	X	X	H*	H*
H	H	—	L	L	NO CHANGE	
H	H	—	H	L	H	L
H	H	—	L	H	L	H
H	H	—	H	H	TOGGLE	
H	H	H	X	X	NO CHANGE	



CD54/74AC/ACT112
FUNCTIONAL DIAGRAM

*Output states unpredictable if \bar{S} and \bar{R} go High simultaneously after both being Low at the same time.

H = High steady state

L = Low steady state

X = Irrelevant

— = High-to-Low transition

— = Low-to-High transition

MAXIMUM RATINGS, Absolute-Maximum Values:

DC SUPPLY-VOLTAGE (V_{cc})	-0.5 to 6 V
DC INPUT DIODE CURRENT, I_{ik} (for $V_i < -0.5$ V or $V_i > V_{cc} + 0.5$ V)	± 20 mA
DC OUTPUT DIODE CURRENT, I_{ok} (for $V_o < -0.5$ V or $V_o > V_{cc} + 0.5$ V)	± 50 mA
DC OUTPUT SOURCE OR SINK CURRENT per Output Pin, I_o (for $V_o > -0.5$ V or $V_o < V_{cc} + 0.5$ V)	± 50 mA
DC V_{cc} or GROUND CURRENT (I_{cc} or I_{GND})	± 100 mA*
POWER DISSIPATION PER PACKAGE (P_D):	
For $T_A = -55$ to $+100^\circ\text{C}$ (PACKAGE TYPE E)	500 mW
For $T_A = +100$ to $+125^\circ\text{C}$ (PACKAGE TYPE E)	Derate Linearly at $8 \text{ mW}/^\circ\text{C}$ to 300 mW
For $T_A = -55$ to $+70^\circ\text{C}$ (PACKAGE TYPE M)	400 mW
For $T_A = +70$ to $+125^\circ\text{C}$ (PACKAGE TYPE M)	Derate Linearly at $6 \text{ mW}/^\circ\text{C}$ to 70 mW
OPERATING-TEMPERATURE RANGE (T_A)	-55 to $+125^\circ\text{C}$
STORAGE TEMPERATURE (T_{stg})	-65 to $+150^\circ\text{C}$
LEAD TEMPERATURE (DURING SOLDERING):	
At distance $1/16 \pm 1/32$ in. (1.59 ± 0.79 mm) from case for 10 s maximum	$+265^\circ\text{C}$
Unit inserted into PC board min. thickness $1/16$ in. (1.59 mm) with solder contacting lead tips only	$+300^\circ\text{C}$

*For up to 4 outputs per device, add ± 25 mA for each additional output.

RECOMMENDED OPERATING CONDITIONS:

For maximum reliability, normal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTICS	LIMITS		UNITS
	MIN.	MAX.	
Supply-Voltage Range, V_{cc} *: (For T_A = Full Package-Temperature Range)			
AC Types	1.5	5.5	V
ACT Types	4.5	5.5	V
DC Input or Output Voltage, V_i , V_o	0	V_{cc}	V
Operating Temperature, T_A	-55	+125	$^\circ\text{C}$
Input Rise and Fall Slew Rate, dt/dv at 1.5 V to 3 V (AC Types) at 3.6 V to 5.5 V (AC Types) at 4.5 V to 5.5 V (ACT Types)	0	50	ns/V
	0	20	ns/V
	0	10	ns/V

*Unless otherwise specified, all voltages are referenced to ground

**CD54/74AC109, CD54/74AC112
CD54/74ACT109, CD54/74ACT112**

STATIC ELECTRICAL CHARACTERISTICS: AC Series

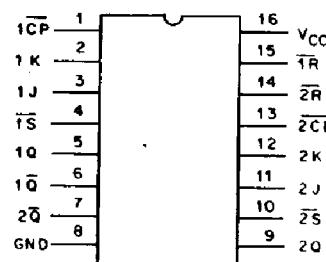
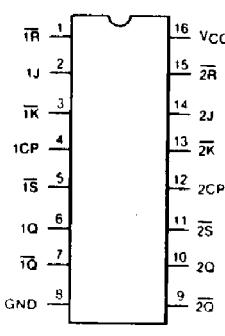
CHARACTERISTICS	TEST CONDITIONS	V_{cc} (V)	AMBIENT TEMPERATURE (T_A) - °C						UNITS	
			+25		-40 to +85		-55 to +125			
			MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
High-Level Input Voltage	V_{IH}		1.5	1.2	—	1.2	—	1.2	V	
			3	2.1	—	2.1	—	2.1		
			5.5	3.85	—	3.85	—	3.85		
Low-Level Input Voltage	V_{IL}		1.5	—	0.3	—	0.3	—	V	
			3	—	0.9	—	0.9	—		
			5.5	—	1.65	—	1.65	—		
High-Level Output Voltage	V_{OH}	V_{IH} or V_{IL} #, * { }	-0.05	1.5	1.4	—	1.4	—	V	
			-0.05	3	2.9	—	2.9	—		
			-0.05	4.5	4.4	—	4.4	—		
			-4	3	2.58	—	2.48	—		
			-24	4.5	3.94	—	3.8	—		
			-75	5.5	—	—	3.85	—		
			-50	5.5	—	—	—	3.85		
Low-Level Output Voltage	V_{OL}	V_{IH} or V_{IL} #, * { }	0.05	1.5	—	0.1	—	0.1	V	
			0.05	3	—	0.1	—	0.1		
			0.05	4.5	—	0.1	—	0.1		
			12	3	—	0.36	—	0.44		
			24	4.5	—	0.36	—	0.44		
			75	5.5	—	—	—	1.65		
			50	5.5	—	—	—	—		
Input Leakage Current	I_I	V_{cc} or GND		5.5	—	±0.1	—	±1	—	±1 μA
Quiescent Supply Current, FF	I_{cc}	V_{cc} or GND	0	5.5	—	4	—	40	—	80 μA

#Test one output at a time for a 1-second maximum duration. Measurement is made by forcing current and measuring voltage to minimize power dissipation.

*Test verifies a minimum 50-ohm transmission-line-drive capability at +85°C, 75 ohms at +125°C.

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TERMINAL ASSIGNMENT DIAGRAMS



CD54/74AC/ACT109

CD54/74AC/ACT112

Technical Data

**CD54/74AC109, CD54/74AC112
CD54/74ACT109, CD54/74ACT112**

STATIC ELECTRICAL CHARACTERISTICS: ACT Series

CHARACTERISTICS	TEST CONDITIONS	V_{cc} (V)	AMBIENT TEMPERATURE (T_A) - °C						UNITS		
			+25		-40 to +85		-55 to +125				
			MIN.	MAX.	MIN.	MAX.	MIN.	MAX.			
High-Level Input Voltage	V_{IH}		4.5 to 5.5	2	—	2	—	2	—	V	
Low-Level Input Voltage	V_{IL}		4.5 to 5.5	—	0.8	—	0.8	—	0.8	V	
High-Level Output Voltage	V_{OH}	V_{IH} or V_{IL} #, *	-0.05 -24 -75 -50	4.5 4.5 5.5 5.5	4.4 3.94 — —	— 3.8 3.85 —	4.4 3.7 — 3.85	— — — —	— — — —	V	
Low-Level Output Voltage	V_{OL}	V_{IH} or V_{IL} #, *	0.05 24 75 50	4.5 4.5 5.5 5.5	— — — —	0.10 0.36 — —	— 0.44 1.65 —	0.10 0.50 — 1.65	— — — —	V	
Input Leakage Current	I_I	V_{cc} or GND		5.5	—	±0.1	—	±1	—	±1	μA
Quiescent Supply Current, FF	I_{cc}	V_{cc} or GND	0	5.5	—	4	—	40	—	80	μA
Additional Supply Current per Input Pin TTL Inputs High 1 Unit Load	ΔI_{cc}	V_{cc} -2.1		4.5 to 5.5	—	2.4	—	2.8	—	3	mA

#Test one output at a time for a 1-second maximum duration. Measurement is made by forcing current and measuring voltage to minimize power dissipation.

*Test verifies a minimum 50-ohm transmission-line-drive capability at +85°C, 75 ohms at +125°C.

ACT INPUT LOADING TABLE

INPUT	UNIT LOADS*	
	109	112
J, CP, \overline{CP}	1	1
K	—	0.53
\overline{K}	0.53	—
S, \overline{R}	0.58	0.58

*Unit load is ΔI_{cc} limit specified in Static Characteristics Chart, e.g., 2.4 mA max. @ 25°C.

CD54/74AC109, CD54/74AC112 CD54/74ACT109, CD54/74ACT112

PREREQUISITE FOR SWITCHING: AC Series

CHARACTERISTICS	SYMBOL	V_{CC} (V)	AMBIENT TEMPERATURE (T_A) - °C				UNITS	
			-40 to +85		-55 to +125			
			MIN.	MAX.	MIN.	MAX.		
Maximum CP, (CP) Frequency 109	f_{max}	1.5	9	—	8	—	MHz	
		3.3*	81	—	71	—		
		5†	114	—	100	—		
112	f_{max}	1.5	9	—	8	—	MHz	
		3.3	81	—	71	—		
		5	114	—	100	—		
CP, (CP) Pulse Width	t_w	1.5	55	—	63	—	ns	
		3.3	6	—	7	—		
		5	4.4	—	5	—		
\bar{R}, \bar{S} Pulse Width	t_w	1.5	49	—	56	—	ns	
		3.3	5.5	—	6.3	—		
		5	3.9	—	4.5	—		
Setup Time J, K to CP 109	t_{su}	1.5	61	—	69	—	ns	
		3.3	6.8	—	7.7	—		
		5	4.8	—	5.5	—		
J, K to \bar{CP} 112	t_{su}	1.5	44	—	50	—	ns	
		3.3	4.9	—	5.6	—		
		5	3.5	—	4	—		
Hold Time J, K to CP 109	t_H	1.5	0	—	0	—	ns	
		3.3	0	—	0	—		
		5	0	—	0	—		
J, K to \bar{CP} 112	t_H	1.5	0	—	0	—	ns	
		3.3	0	—	0	—		
		5	0	—	0	—		
Removal Time R, S to CP, (CP)	t_{REM}	1.5	27	—	31	—	ns	
		3.1	3.1	—	3.5	—		
		5	2.2	—	2.5	—		

*3.3 V: min. is @ 3 V

†5 V: min is @ 4.5 V

SWITCHING CHARACTERISTICS: AC Series; $I_L, I_F = 3$ ns, $C_L = 50$ pF

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CHARACTERISTICS	SYMBOL	V_{CC} (V)	AMBIENT TEMPERATURE (T_A) - °C				UNITS	
			-40 to +85		-55 to +125			
			MIN.	MAX.	MIN.	MAX.		
Propagation Delays: CP, (CP) to Q, \bar{Q}	t_{PLH} t_{PHL}	1.5	—	117	—	129	ns	
		3.3*	3.7	13.1	3.6	14.4		
		5†	2.7	9.4	2.6	10.3		
S, R to Q, \bar{Q}	t_{PLH} t_{PHL}	1.5	—	139	—	153	ns	
		3.3	4.4	15.5	4.3	17.1		
		5	3.2	11.1	3.1	12.2		
Power Dissipation Capacitance	$C_{PD\$}$	—	56 Typ.		56 Typ.		pF	
Input Capacitance	C_I	—	—	10	—	10	pF	

*3.3 V: min. is @ 3.6 V

max. is @ 3 V

†5 V: min. is @ 5.5 V

max. is @ 4.5 V

 $\$C_{PD}$ is used to determine the dynamic power consumption, per flip-flop.

$$P_D = C_{PD} V_{CC}^2 f_i + \Sigma (C_L V_{CC}^2 f_o) \text{ where } f_i = \text{input frequency}$$

 $f_o = \text{output frequency}$ $C_L = \text{output load capacitance}$ $V_{CC} = \text{supply voltage.}$

Technical Data

**CD54/74AC109, CD54/74AC112
CD54/74ACT109, CD54/74ACT112**

PREREQUISITE FOR SWITCHING: ACT Series

CHARACTERISTICS	SYMBOL	V_{CC} (V)	AMBIENT TEMPERATURE (T_A) - °C				UNITS	
			-40 to +85		-55 to +125			
			MIN.	MAX.	MIN.	MAX.		
Maximum CP, (CP) Frequency 109 112	f_{max}	5*	114	—	100	—	MHz	
			114	—	100	—		
CP, (CP) Pulse Width	t_w	5	4.4	—	5	—	ns	
R, S Pulse Width	t_w	5	4.8	—	5.5	—	ns	
Setup Time J, K to CP (109) J, K to $\bar{C}P$ (112)	t_{SU}	5	4.8	—	5.5	—	ns	
			3.5	—	4	—		
Hold Time J, K to CP (109) J, K to $\bar{C}P$ (112)	t_H	5	0	—	0	—	ns	
			1	—	1	—		
Removal Time R, S to CP, ($\bar{C}P$)	t_{REM}	5	2.2	—	2.5	—	ns	

*5 V: min. is @ 4.5 V

SWITCHING CHARACTERISTICS: ACT Series; t_i , t_o = 3 ns, C_L = 50 pF

CHARACTERISTICS	SYMBOL	V_{CC} (V)	AMBIENT TEMPERATURE (T_A) - °C				UNITS	
			-40 to +85		-55 to +125			
			MIN.	MAX.	MIN.	MAX.		
Propagation Delays CP, (CP) to Q, Q S, R, to Q, Q	t_{PLH} t_{PHL}	5*	2.7	9.4	2.6	10.3	ns	
			3.2	11.1	3.1	12.2		
Power Dissipation Capacitance	$C_{PD\$}$	—	56 Typ.		56 Typ.		pF	
Input Capacitance	C_i	—	—	10	—	10	pF	

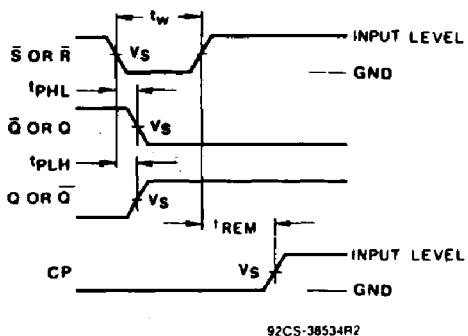
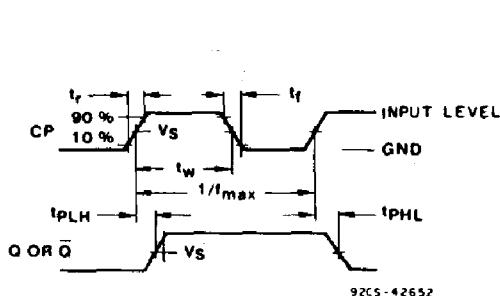
*5 V: min. is @ 5.5 V
max. is @ 4.5 V

§ C_{PD} is used to determine the dynamic power consumption, per flip-flop.

$$P_D = C_{PD} V_{CC}^2 f_i + \sum (C_L V_{CC}^2 f_o) + V_{CC} \Delta I_{CC} \quad \text{where } f_i = \text{input frequency} \\ f_o = \text{output frequency} \\ C_L = \text{output load capacitance} \\ V_{CC} = \text{supply voltage.}$$

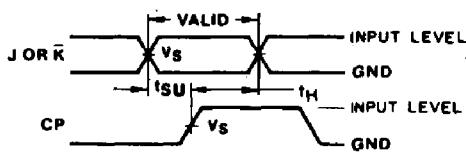
CD54/74AC109, CD54/74AC112 CD54/74ACT109, CD54/74ACT112

CD54/74AC/ACT109 Waveforms



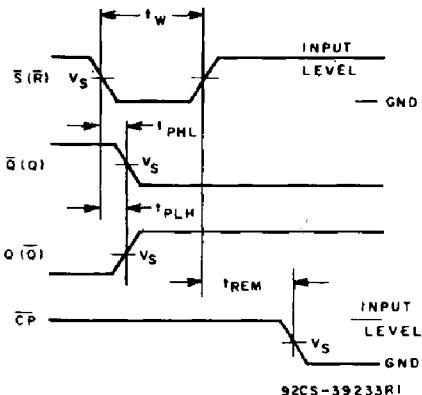
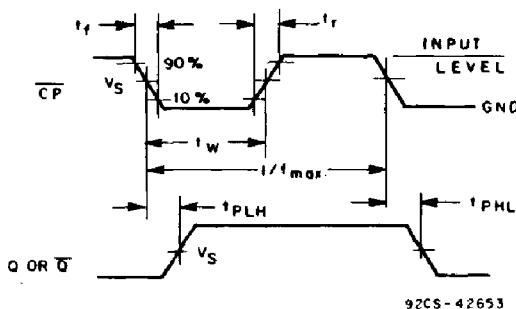
Clock to output delays and clock pulse width.

Reset or Set prerequisite and propagation delays.

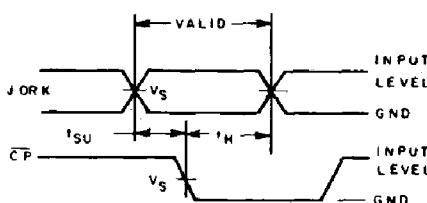


Data setup and hold times.

CD54/74AC/ACT112 Waveforms



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Propagation delay times, and setup and hold times.

*FOR AC SERIES ONLY: WHEN
 $V_{CC} = 1.5\text{ V}$, $R_L = 1\text{ k}\Omega$

92CS-42189

Test circuit.

	CD54/74AC	CD54/74ACT
Input Level	V_{CC}	3 V
Input Switching Voltage, V_S	$0.5 V_{CC}$	1.5 V
Output Switching Voltage, V_S	$0.5 V_{CC}$	$0.5 V_{CC}$

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